

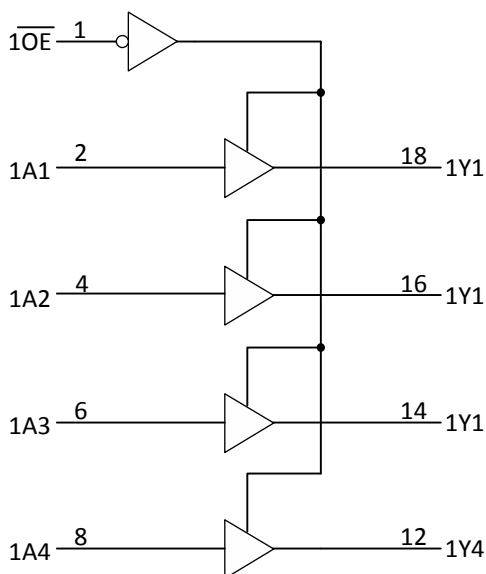
SNx4HC244 3 ステート出力、オクタール・バッファ/ライン・ドライバ

1 特長

- 広い動作電圧範囲: 2V~6V
- 大電流出力は最大 15 個の LSTTL 負荷を駆動可能
- バス・ラインまたはバッファ・メモリ・アドレス・レジスタを駆動できる 3 ステート出力
- 低い消費電力: $I_{CC} = 80\mu\text{A}$ (最大値)
- $t_{pd} = 11\text{ns}$ (標準値)
- 5V で $\pm 6\text{mA}$ の出力駆動能力
- 低い入力電流: 最大値 $1\mu\text{A}$
- MIL-PRF-38535 準拠の製品については、特に記述のない限り、すべてのパラメータはテスト済みです。他のすべての製品については、量産プロセスにすべてのパラメータのテストが含まれているとは限りません。

2 アプリケーション

- サーバー
- LED ディスプレイ
- ネットワーク・スイッチ
- 通信インフラ
- モータ・ドライバ
- I/O エクスパンダ



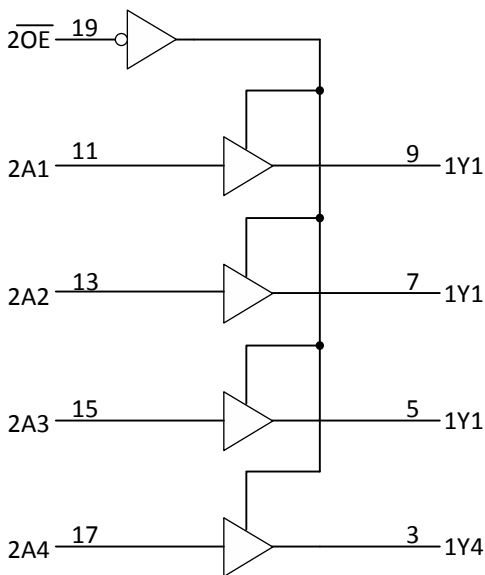
3 概要

SNx4HC244 オクタール・バッファ/ライン・ドライバは、3 ステート・メモリ・アドレス・ドライバ、クロック・ドライバ、バス用レシーバ/トランスミッタの性能と密度の両方を向上することに特化して設計されています。SNx4HC244 デバイスは、独立した出力イネーブル (\overline{OE}) 入力を備えた 2 つの 4 ビット・バッファ/ドライバで構成されています。 \overline{OE} が LOW の場合、デバイスは A 入力からの非反転型データを Y 出力に渡します。 \overline{OE} が HIGH の場合、出力は高インピーダンス状態になります。

製品情報

部品番号	パッケージ (ピン数) ⁽¹⁾	本体サイズ (公称)
SN54HC244	CDIP (20)	6.92mm × 24.38mm
	CFP (20)	6.92mm × 13.72mm
	LCCC (20)	8.89mm × 8.89mm
SN74HC244DB	SSOP (20)	5.30mm × 7.25mm
SN74HC244DW	SOIC (20)	7.50mm × 12.80mm
SN74HC244N	PDIP (20)	6.30mm × 25.40mm
SN74HC244NS	SOP (20)	5.30mm × 12.60mm
SN74HC244PW	TSSOP (20)	4.40mm × 6.50mm

(1) 利用可能なパッケージについては、このデータシートの末尾にある注文情報を参照してください。



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論理図 (正論理)



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision E (May 2016) to Revision F (May 2022)	Page
• Junction-to-ambient thermal resistance values increased to match current function.....	5

Changes from Revision D (August 2003) to Revision E (May 2016)	Page
• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。.....	1
• 「特長」セクションに軍事利用についての免責事項を追加。.....	1
• 「アプリケーション」セクションを追加.....	1
• 「注文情報」表を削除.....	1
• 「製品情報」表を追加.....	1

5 Pin Configuration and Functions

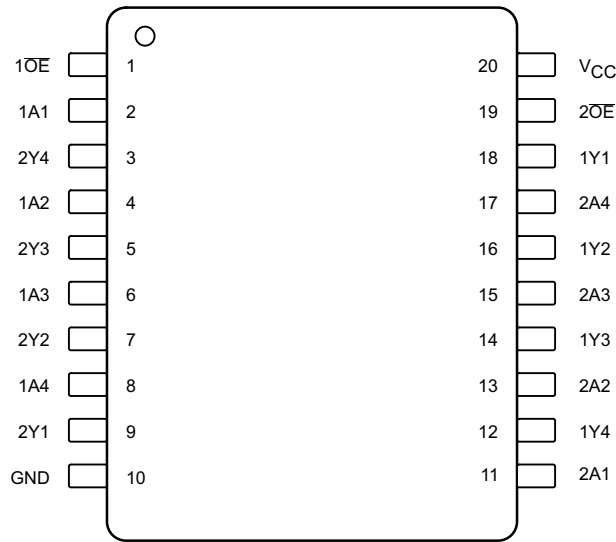


FIG 5-1. DB, DW, J, N, NS, PW, W Package 20-Pin SSOP, SOIC, CDIP, PDIP, SOP, TSSOP, or CFP Top View

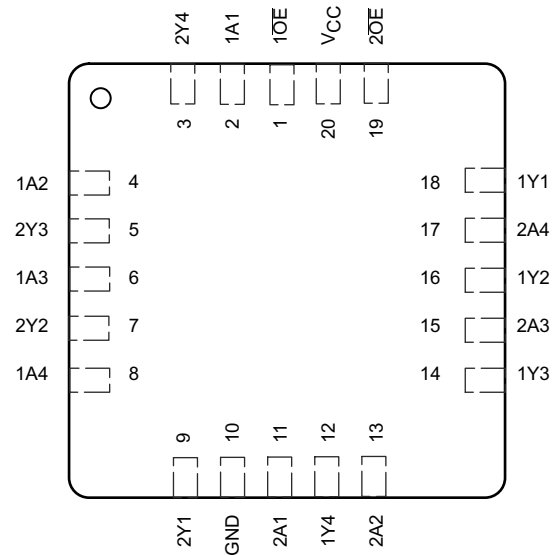


FIG 5-2. FK Package 20-Pin LCCC Top View

Pin Functions

PIN		I/O ⁽¹⁾	DESCRIPTION
NO.	NAME		
1	1 \overline{OE}	I	Output Enable
2	1A1	I	Input
3	2Y4	O	Output
4	1A2	I	Input
5	2Y3	O	Output
6	1A3	I	Input
7	2Y2	O	Output
8	1A4	I	Input
9	2Y1	O	Output
10	GND	—	Ground
11	2A1	I	Input
12	1Y4	O	Output
13	2A2	I	Input
14	1Y3	O	Output
15	2A3	I	Input
16	1Y2	O	Output
17	2A4	I	Input
18	1Y1	O	Output
19	2 \overline{OE}	I	Output Enable
20	V _{CC}	—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage range, V_{CC}		-0.5	7	V
Input clamp current, I_{IK}	$V_I < 0$ or $V_I > V_{CC}$ ⁽²⁾		±20	mA
Output clamp current, I_{OK}	$V_O < 0$ or $V_O > V_{CC}$ ⁽²⁾		±20	mA
Continuous output current, I_O	$V_O = 0$ or V_{CC}		±35	mA
Continuous current through V_{CC} or GND			±70	mA
Junction Temperature, T_J			150	°C
Storage temperature, T_{stg}		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

		SN74HC244	VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5		V
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 6$ V	4.2		
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0.5	V
		$V_{CC} = 4.5$ V		1.35	
		$V_{CC} = 6$ V		1.8	
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise and fall time	$V_{CC} = 2$ V		1000	ns/V
		$V_{CC} = 4.5$ V		500	
		$V_{CC} = 6$ V		400	
C_{pd}	Power dissipation capacitance per buffer or driver (no load)		35		pF
T_A	Operating free-air temperature	SN54HC244	-55	125	°C
		SN74HC244	-40	85	

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the Texas Instruments application report, *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

6.4 Thermal Information

THERMAL METRIC		SN74HC244					UNIT
		DW (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	
		20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance ⁽¹⁾	109.1	122.7	84.6	113.4	131.8	°C/W
$R_{\theta JC (top)}$	Junction-to-case (top) thermal resistance	76	81.6	72.5	78.6	72.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	77.6	77.5	65.3	78.4	82.8	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	51.5	46.1	55.3	47.1	21.5	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	77.1	77.1	65.2	78.1	82.4	°C/W
$R_{\theta JC (bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu\text{A}$	$V_{CC} = 2 \text{ V}$	1.9	1.998	V
			$V_{CC} = 4.5 \text{ V}$	4.4	4.499	
			$V_{CC} = 6 \text{ V}$	5.9	5.999	
		$I_{OH} = -6 \text{ mA}, V_{CC} = 4.5 \text{ V}$	3.98	4.3		
		$I_{OH} = -7.8 \text{ mA}, V_{CC} = 6 \text{ V}$	5.48	5.8		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu\text{A}$	$V_{CC} = 2 \text{ V}$	0.002	0.1	V
			$V_{CC} = 4.5 \text{ V}$	0.001	0.1	
			$V_{CC} = 6 \text{ V}$	0.001	0.1	
		$I_{OL} = 6 \text{ mA}, V_{CC} = 4.5 \text{ V}$	0.17	0.26		
		$I_{OL} = 7.8 \text{ mA}, V_{CC} = 6 \text{ V}$	0.15	0.26		
I_I	$V_I = V_{CC}$ or 0, $V_{CC} = 6 \text{ V}$			± 0.1	± 100	nA
I_{OZ}	$V_O = V_{CC}$ or 0, $V_I = V_{IH}$ or V_{IL} , $V_{CC} = 6 \text{ V}$			± 0.01	± 0.5	μA
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$, $V_{CC} = 6 \text{ V}$				8	μA
C_i	$V_{CC} = 2 \text{ V to } 6 \text{ V}$			3	10	pF

6.6 Electrical Characteristics – SN54HC244

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu\text{A}$	$V_{CC} = 2 \text{ V}$	1.9		V
			$V_{CC} = 4.5 \text{ V}$	4.4		
			$V_{CC} = 6 \text{ V}$	5.9		
		$I_{OH} = -6 \text{ mA}, V_{CC} = 4.5 \text{ V}$	3.7			
		$I_{OH} = -7.8 \text{ mA}, V_{CC} = 6 \text{ V}$	5.2			

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu\text{A}$	$V_{CC} = 2 \text{ V}$		0.1	V
			$V_{CC} = 4.5 \text{ V}$		0.1	
			$V_{CC} = 6 \text{ V}$		0.1	
		$I_{OL} = 6 \text{ mA}, V_{CC} = 4.5 \text{ V}$			0.4	
		$I_{OL} = 7.8 \text{ mA}, V_{CC} = 6 \text{ V}$			0.4	
I_I	$V_I = V_{CC}$ or 0, $V_{CC} = 6 \text{ V}$				± 1000	nA
I_{OZ}	$V_O = V_{CC}$ or 0, $V_I = V_{IH}$ or V_{IL} , $V_{CC} = 6 \text{ V}$				± 10	μA
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$, $V_{CC} = 6 \text{ V}$				160	μA
C_i	$V_{CC} = 2 \text{ V}$ to 6 V				10	pF

6.7 Electrical Characteristics – SN74HC244

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu\text{A}$	$V_{CC} = 2 \text{ V}$	1.9		V
			$V_{CC} = 4.5 \text{ V}$	4.4		
			$V_{CC} = 6 \text{ V}$	5.9		
		$I_{OH} = -6 \text{ mA}, V_{CC} = 4.5 \text{ V}$		3.84		
		$I_{OH} = -7.8 \text{ mA}, V_{CC} = 6 \text{ V}$		5.34		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu\text{A}$	$V_{CC} = 2 \text{ V}$		0.1	V
			$V_{CC} = 4.5 \text{ V}$		0.1	
			$V_{CC} = 6 \text{ V}$		0.1	
		$I_{OL} = 6 \text{ mA}, V_{CC} = 4.5 \text{ V}$			0.33	
		$I_{OL} = 7.8 \text{ mA}, V_{CC} = 6 \text{ V}$			0.33	
I_I	$V_I = V_{CC}$ or 0, $V_{CC} = 6 \text{ V}$				± 1000	nA
I_{OZ}	$V_O = V_{CC}$ or 0, $V_I = V_{IH}$ or V_{IL} , $V_{CC} = 6 \text{ V}$				± 5	μA
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$, $V_{CC} = 6 \text{ V}$				80	μA
C_i	$V_{CC} = 2 \text{ V}$ to 6 V				10	pF

6.8 Switching Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise noted; see [7-1](#))

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{pd}	From A (input) to Y (output)	$V_{CC} = 2 \text{ V}$	$C_L = 50 \text{ pF}$	40	115	ns
			$C_L = 150 \text{ pF}$	56	165	
		$V_{CC} = 4.5 \text{ V}$	$C_L = 50 \text{ pF}$	13	23	
			$C_L = 150 \text{ pF}$	18	33	
		$V_{CC} = 6 \text{ V}$	$C_L = 50 \text{ pF}$	11	20	
			$C_L = 150 \text{ pF}$	15	28	
t_{en}	From \overline{OE} (input) to Y (output)	$V_{CC} = 2 \text{ V}$	$C_L = 50 \text{ pF}$	75	150	ns
			$C_L = 150 \text{ pF}$	100	200	
		$V_{CC} = 4.5 \text{ V}$	$C_L = 50 \text{ pF}$	15	30	
			$C_L = 150 \text{ pF}$	20	40	
		$V_{CC} = 6 \text{ V}$	$C_L = 50 \text{ pF}$	13	26	
			$C_L = 150 \text{ pF}$	17	34	

$T_A = 25^\circ\text{C}$ (unless otherwise noted; see [7-1](#))

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{dis}	From \overline{OE} (input) to Y (output)	$V_{CC} = 2\text{ V}$	$C_L = 50\text{ pF}$	75	150	ns
		$V_{CC} = 4.5\text{ V}$	$C_L = 50\text{ pF}$	15	30	
		$V_{CC} = 6\text{ V}$	$C_L = 50\text{ pF}$	13	26	
t_t	To Y (output)	$V_{CC} = 2\text{ V}$	$C_L = 50\text{ pF}$	28	60	ns
			$C_L = 150\text{ pF}$	45	210	
		$V_{CC} = 4.5\text{ V}$	$C_L = 50\text{ pF}$	8	12	
			$C_L = 150\text{ pF}$	17	42	
		$V_{CC} = 6\text{ V}$	$C_L = 50\text{ pF}$	6	10	
			$C_L = 150\text{ pF}$	13	36	

6.9 Switching Characteristics – $C_L = 50 \text{ pF}$

over recommended operating free-air temperature range (unless otherwise noted; see [7-1](#))

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{pd}	From A (input) to Y (output)	$V_{CC} = 2 \text{ V}$	SN54HC244		170	ns
			SN74HC244		145	
		$V_{CC} = 4.5 \text{ V}$	SN54HC244		34	
			SN74HC244		29	
		$V_{CC} = 6 \text{ V}$	SN54HC244		29	
			SN74HC244		25	
t_{en}	From \overline{OE} (input) to Y (output)	$V_{CC} = 2 \text{ V}$	SN54HC244		225	ns
			SN74HC244		190	
		$V_{CC} = 4.5 \text{ V}$	SN54HC244		45	
			SN74HC244		38	
		$V_{CC} = 6 \text{ V}$	SN54HC244		38	
			SN74HC244		32	
t_{dis}	From \overline{OE} (input) to Y (output)	$V_{CC} = 2 \text{ V}$	SN54HC244		225	ns
			SN74HC244		190	
		$V_{CC} = 4.5 \text{ V}$	SN54HC244		45	
			SN74HC244		38	
		$V_{CC} = 6 \text{ V}$	SN54HC244		38	
			SN74HC244		32	
t_t	To Y (output)	$V_{CC} = 2 \text{ V}$	SN54HC244		90	ns
			SN74HC244		75	
		$V_{CC} = 4.5 \text{ V}$	SN54HC244		18	
			SN74HC244		15	
		$V_{CC} = 6 \text{ V}$	SN54HC244		15	
			SN74HC244		13	

6.10 Switching Characteristics – $C_L = 150 \text{ pF}$

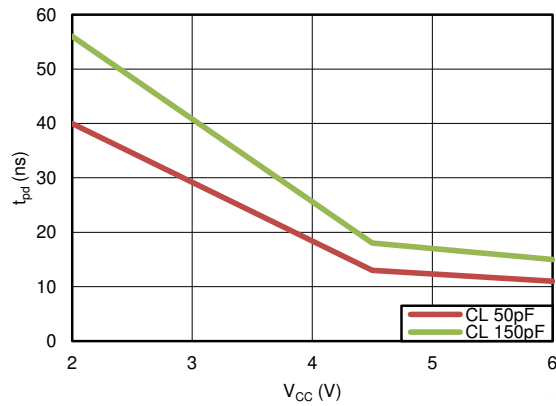
over recommended operating free-air temperature range (unless otherwise noted; see [7-1](#))

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{pd}	From A (input) to Y (output)	$V_{CC} = 2 \text{ V}$	SN54HC244		245	ns
			SN74HC244		210	
		$V_{CC} = 4.5 \text{ V}$	SN54HC244		49	
			SN74HC244		42	
		$V_{CC} = 6 \text{ V}$	SN54HC244		42	
			SN74HC244		35	
t_{en}	From \overline{OE} (input) to Y (output)	$V_{CC} = 2 \text{ V}$	SN54HC244		300	ns
			SN74HC244		250	
		$V_{CC} = 4.5 \text{ V}$	SN54HC244		60	
			SN74HC244		50	
		$V_{CC} = 6 \text{ V}$	SN54HC244		51	
			SN74HC244		43	

over recommended operating free-air temperature range (unless otherwise noted; see [7-1](#))

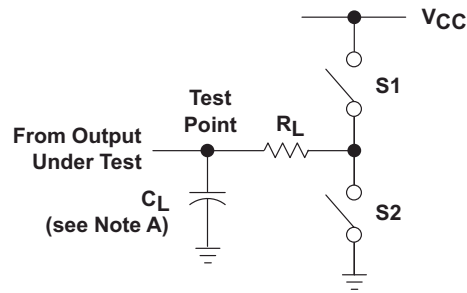
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_t	To Y (output)	$V_{CC} = 2\text{ V}$	SN54HC244		315	ns
			SN74HC244		265	
		$V_{CC} = 4.5\text{ V}$	SN54HC244		63	
			SN74HC244		53	
		$V_{CC} = 6\text{ V}$	SN54HC244		53	
			SN74HC244		45	

6.11 Typical Characteristic

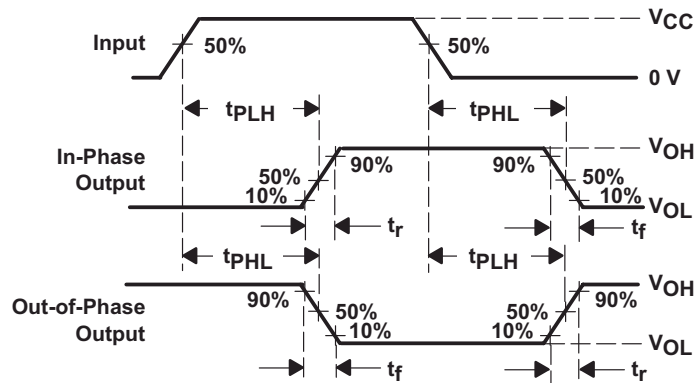


6-1. Propagation Delay

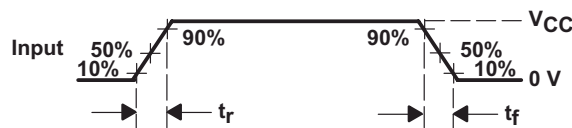
7 Parameter Measurement Information



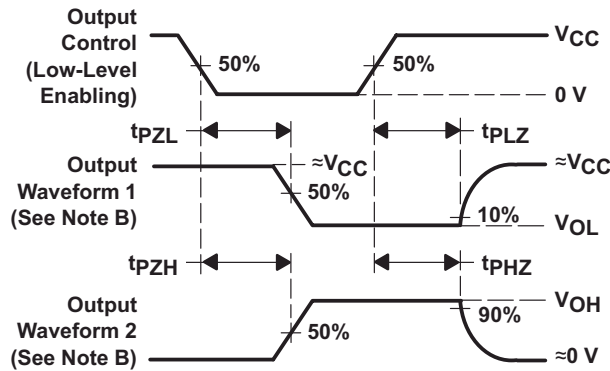
7-1. Load Circuit



7-2. Propagation Delay and Output Transition Times



7-3. Input Rise and Fall Times



7-4. Enable and Disable Times for 3-State Outputs

Note

NOTE:

- A. C_L includes probe and test-fixture capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

表 7-1. Switching Information Table

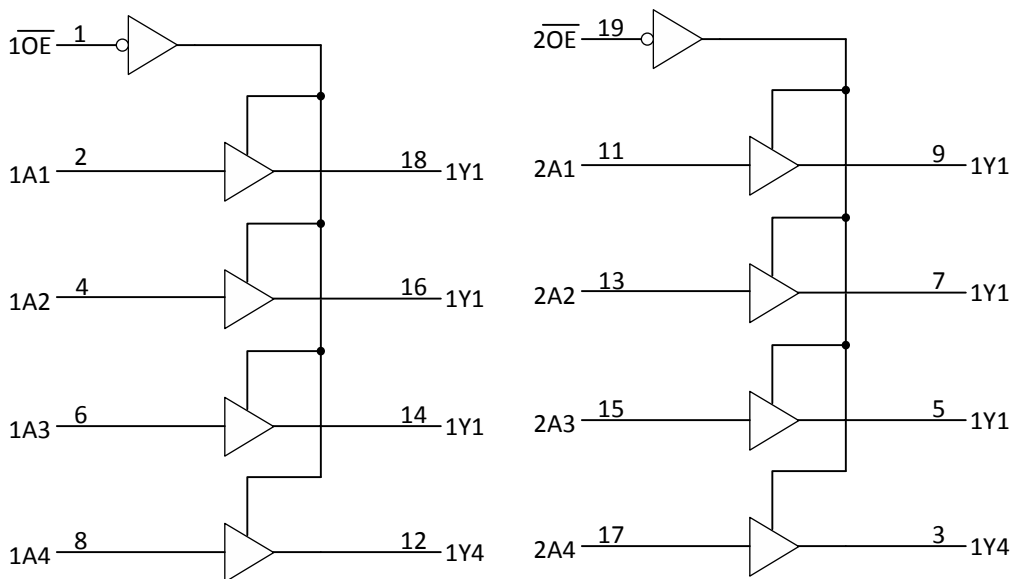
PARAMETER		RL	CL	S1	S2
t_{en}	t_{PZH}	1 k Ω	50 pF or 150 pF	Open	Closed
	t_{PZL}	1 k Ω	50 pF or 150 pF	Closed	Open
t_{dis}	t_{PHZ}	1 k Ω	50 pF	Open	Closed
	t_{PLZ}	1 k Ω	50 pF	Closed	Open
t_{pd} or t_t		—	50 pF or 150 pF	Open	Open

8 Detailed Description

8.1 Overview

The SNx4HC244 device is organized as two 4-bit buffers and line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state. To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

8.2 Functional Block Diagram



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8.3 Feature Description

The SNx4HC244 has a wide operating voltage of 2 V to 6 V. Inputs accept voltage levels up to V_{CC} . This device has a low power consumption of I_{CC} 80 μ A (maximum). The SNx4HC244 device can drive ± 6 mA at V_{CC} of 5 V.

8.4 Device Functional Modes

表 8-1 lists the functions of the SNx4HC244.

表 8-1. Function Table
(Each Buffer or Driver)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z

9 Application and Implementation

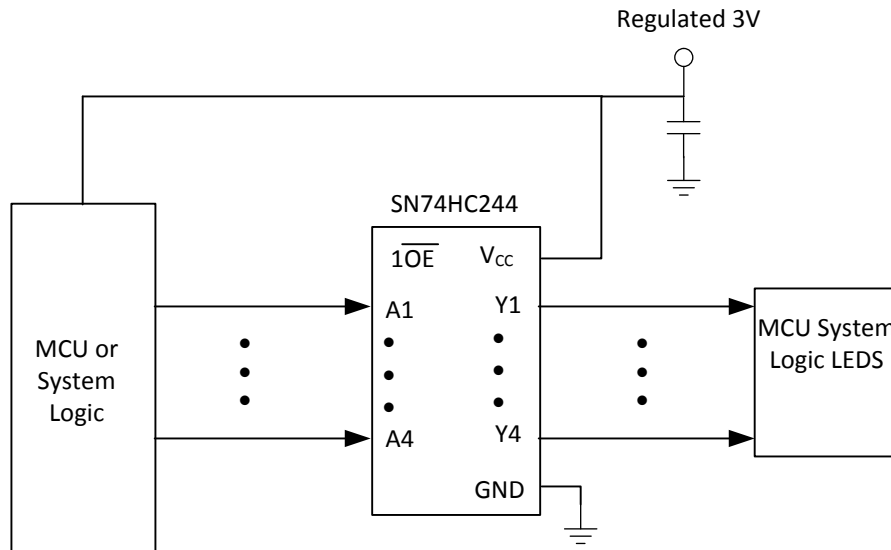
Note

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくこととなります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

9.1 Application Information

SN74HC244 is a high-drive CMOS device that can be used for a multitude of bus interface type applications where output drive or PCB trace length is a concern.

9.2 Typical Application



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図 9-1. SN74HC244 Application Schematic

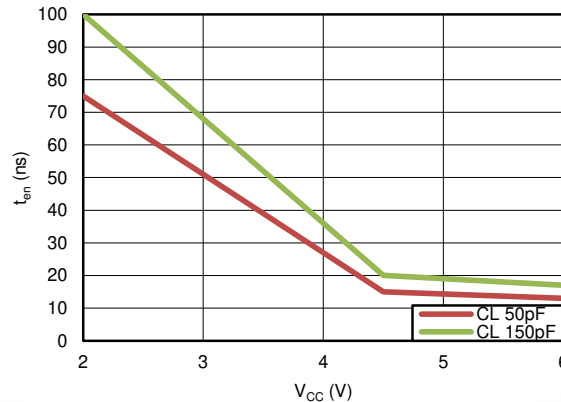
9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive also creates fast edges into light loads so routing and load conditions should be considered to prevent ringing.

9.2.2 Detailed Design Procedure

1. Recommended input conditions:
 - For rise time and fall time specifications, see $\Delta t/\Delta V$ in [セクション 6.3](#).
 - For specified high and low levels, see V_{IH} and V_{IL} in [セクション 6.3](#).
2. Recommend output conditions:
 - Load currents should not exceed I_O max per output and should not exceed the continuous current through V_{CC} or GND total current for the part. These limits are located in [セクション 6.1](#).
 - Outputs should not be pulled above V_{CC} .

9.2.3 Application Curve



9-2. Enable Time

10 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [セクション 6.3](#).

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- μ F capacitor. If there are multiple V_{CC} terminals, then TI recommends 0.01- μ F or 0.022- μ F capacitors for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. Multiple bypass capacitors may be paralleled to reject different frequencies of noise. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

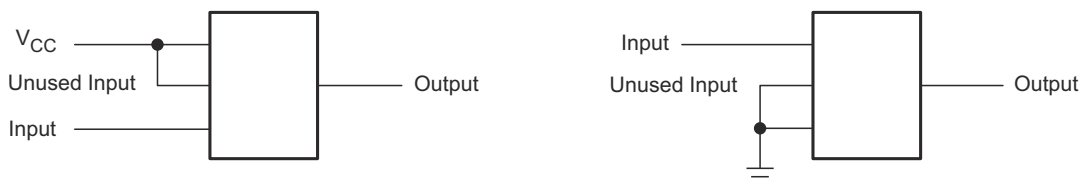
11 Layout

11.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input and gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [9-11-1](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient.

11.2 Layout Example



11-1. Layout Diagram

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Links

表 12-1 lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 12-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54HC244	Click here	Click here	Click here	Click here	Click here
SN74HC244	Click here	Click here	Click here	Click here	Click here

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 サポート・リソース

TI E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の [使用条件](#) を参照してください。

12.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8409601VRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8409601VR A SNV54HC244J	Samples
5962-8409601VSA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8409601VS A SNV54HC244W	Samples
84096012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84096012A SNJ54HC 244FK	Samples
8409601RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8409601RA SNJ54HC244J	Samples
8409601SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8409601SA SNJ54HC244W	Samples
JM38510/65705B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65705B2A	Samples
JM38510/65705BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65705BRA	Samples
JM38510/65705BSA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65705BSA	Samples
M38510/65705B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65705B2A	Samples
M38510/65705BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65705BRA	Samples
M38510/65705BSA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65705BSA	Samples
SN54HC244J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC244J	Samples
SN74HC244APWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244A	Samples
SN74HC244DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85	HC244	
SN74HC244DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC244DWRE4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244DWRG4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC244N	Samples
SN74HC244NE4	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC244N	Samples
SN74HC244NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244NSRG4	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244PW	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85	HC244	
SN74HC244PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244PWRE4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244PWRG4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC244	Samples
SN74HC244PWT	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85	HC244	
SN74HC244QDWRG4Q1	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		HC244Q	Samples
SNJ54HC244FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84096012A SNJ54HC 244FK	Samples
SNJ54HC244J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8409601RA SNJ54HC244J	Samples
SNJ54HC244W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8409601SA SNJ54HC244W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC244, SN54HC244-SP, SN74HC244 :

- Catalog : [SN74HC244](#), [SN54HC244](#)

- Automotive : [SN74HC244-Q1](#), [SN74HC244-Q1](#)

- Enhanced Product : [SN74HC244-EP](#), [SN74HC244-EP](#)

- Military : [SN54HC244](#)

- Space : [SN54HC244-SP](#)

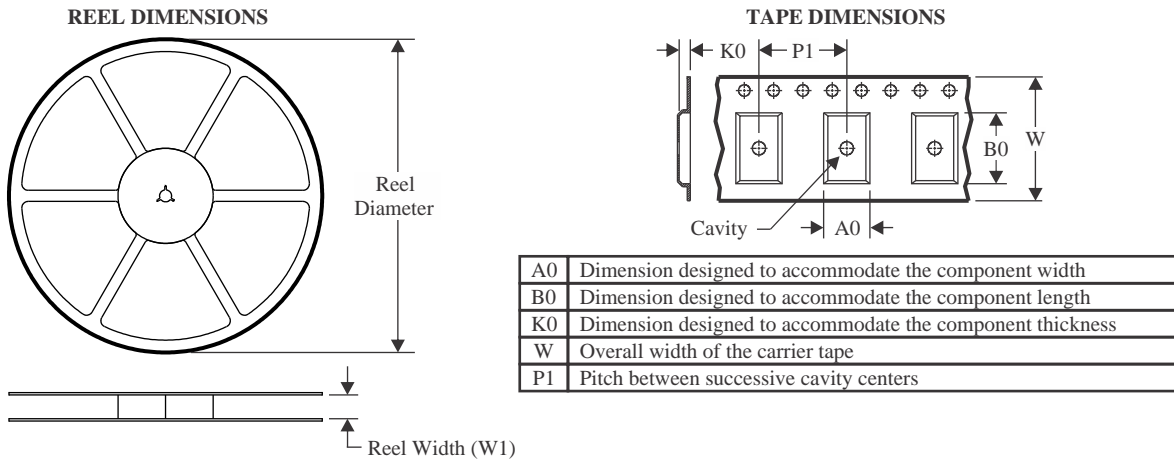
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

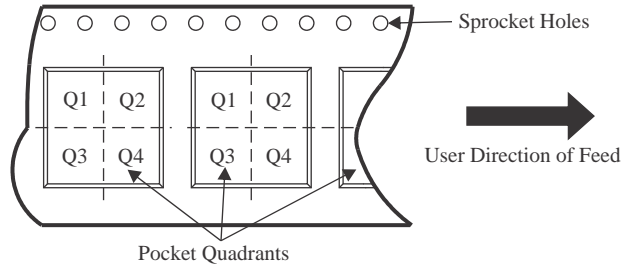
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

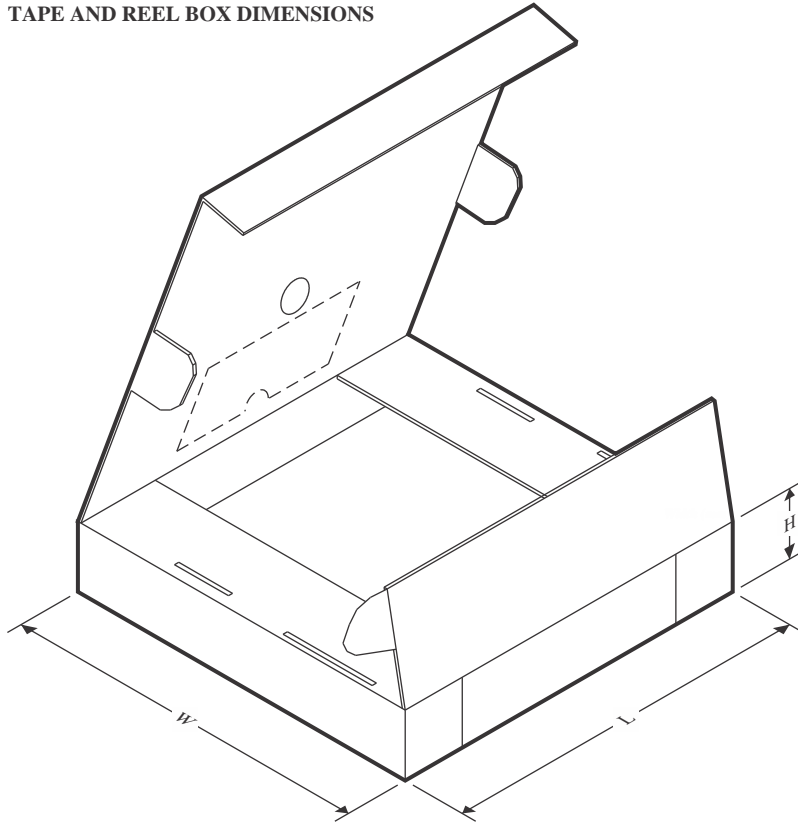


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



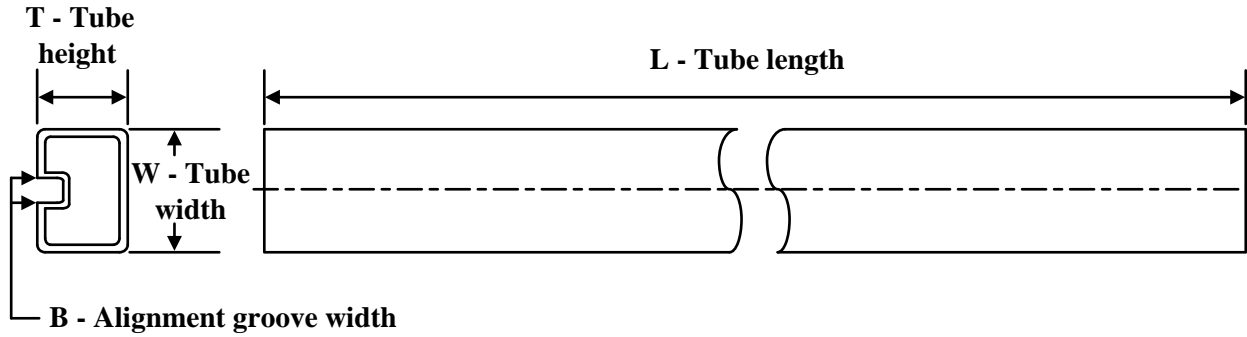
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC244APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74HC244APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74HC244DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74HC244DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74HC244DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74HC244DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC244DWRG4	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC244NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74HC244NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74HC244PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74HC244PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74HC244QDWRG4Q1	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC244APWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74HC244APWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74HC244DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74HC244DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74HC244DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC244DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC244DWRG4	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC244NSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74HC244NSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74HC244PWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74HC244PWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74HC244QDWRG4Q1	SOIC	DW	20	2000	367.0	367.0	45.0

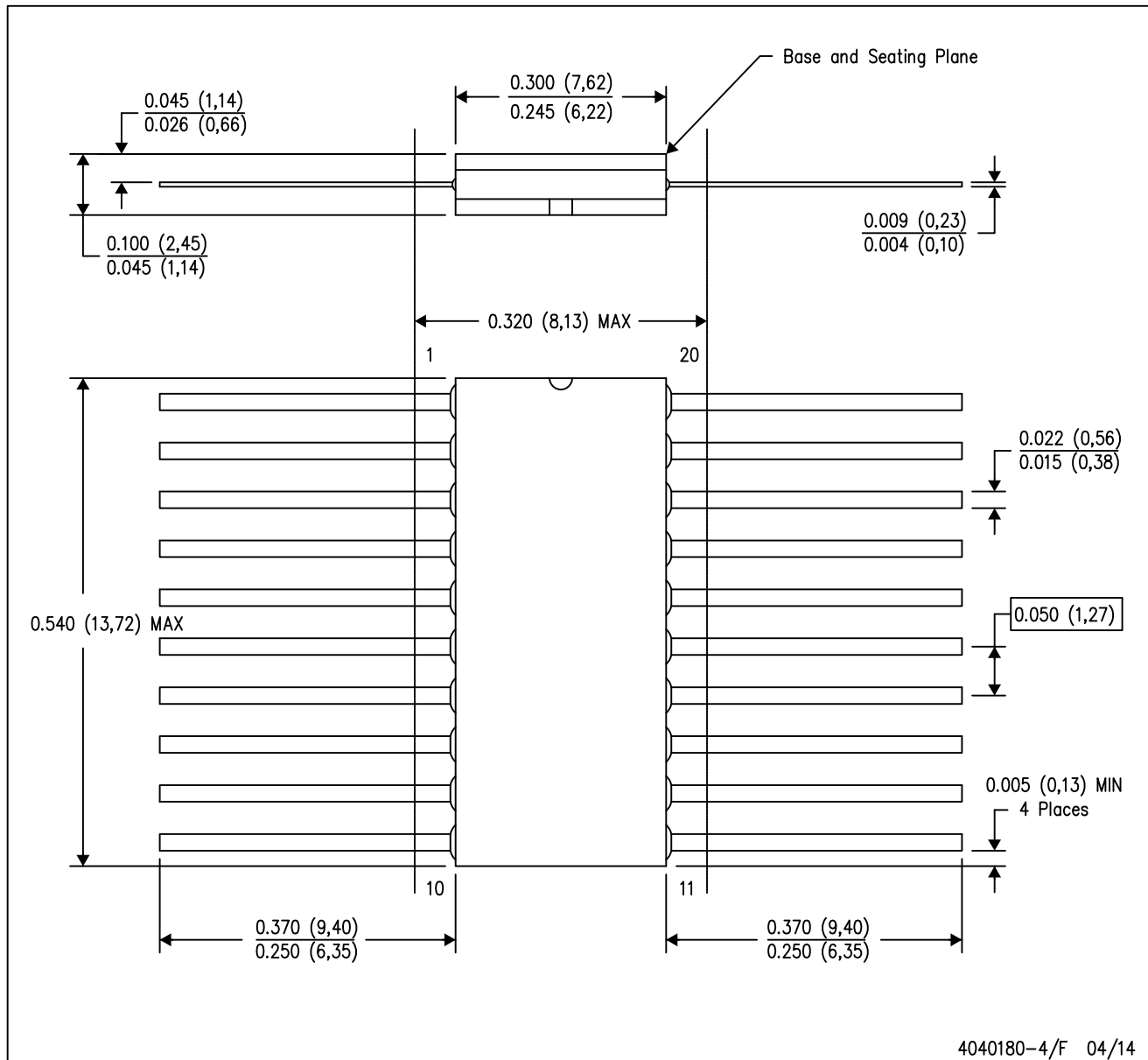
TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-8409601VSA	W	CFP	20	25	506.98	26.16	6220	NA
84096012A	FK	LCCC	20	55	506.98	12.06	2030	NA
8409601SA	W	CFP	20	25	506.98	26.16	6220	NA
JM38510/65705B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/65705BSA	W	CFP	20	25	506.98	26.16	6220	NA
M38510/65705B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/65705BSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74HC244N	N	PDIP	20	20	506	13.97	11230	4.32
SN74HC244NE4	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54HC244FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC244W	W	CFP	20	25	506.98	26.16	6220	NA

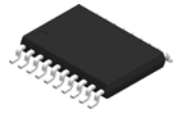
W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

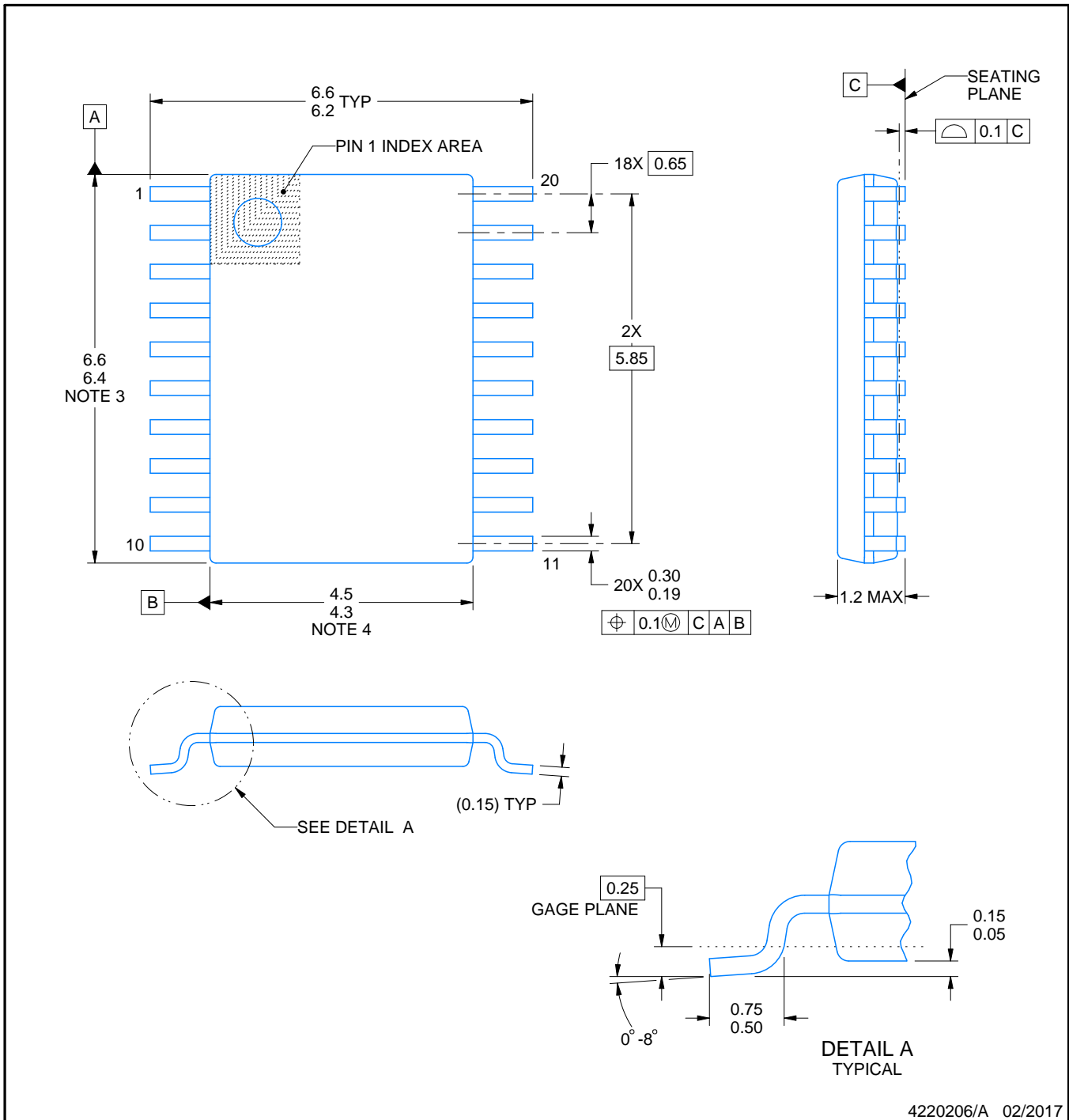
PW0020A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220206/A 02/2017

NOTES:

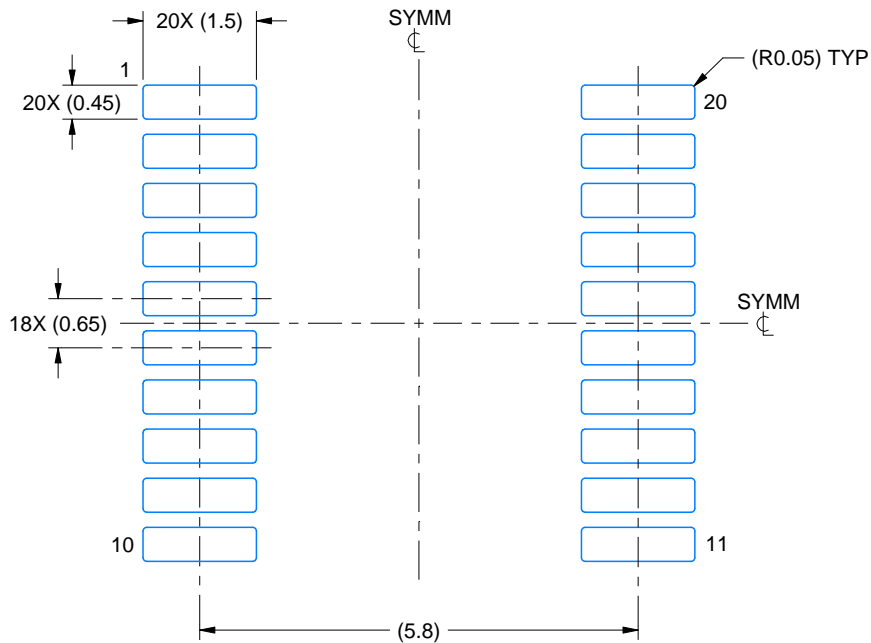
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

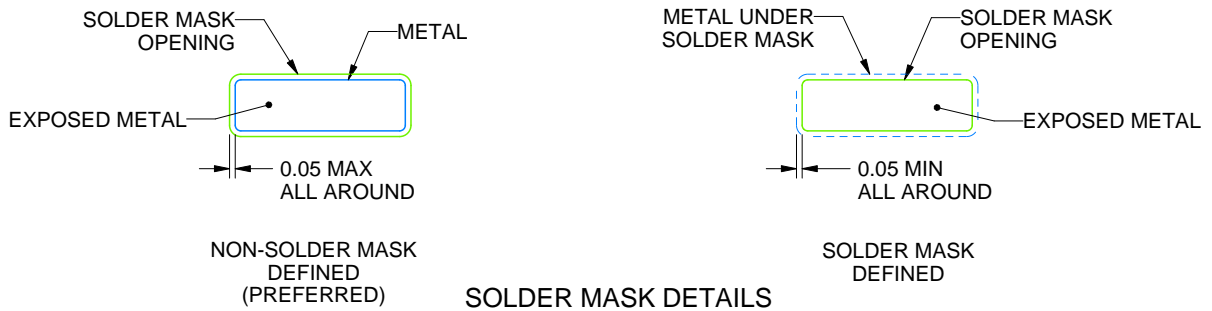
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

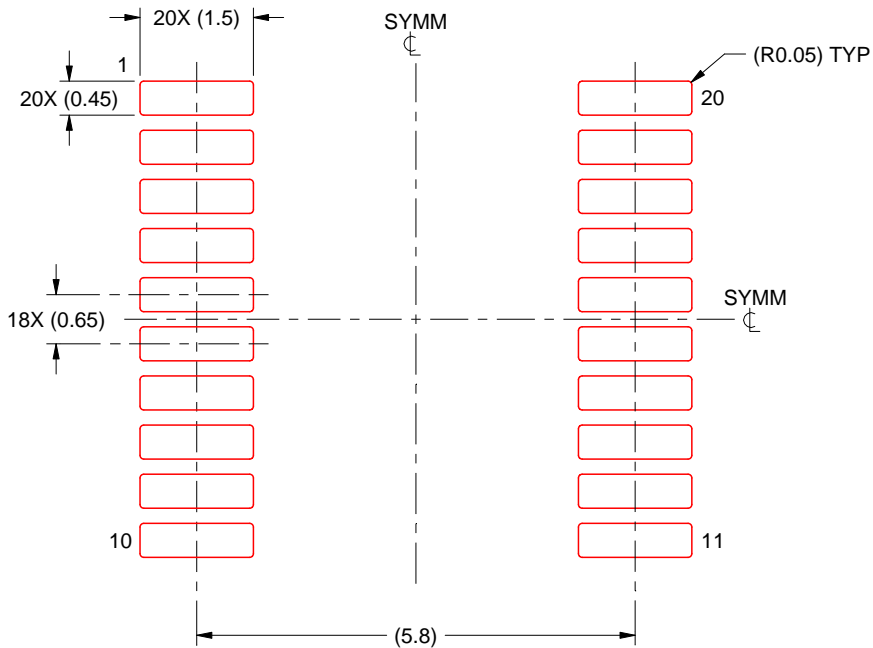
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



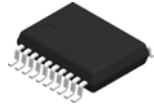
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

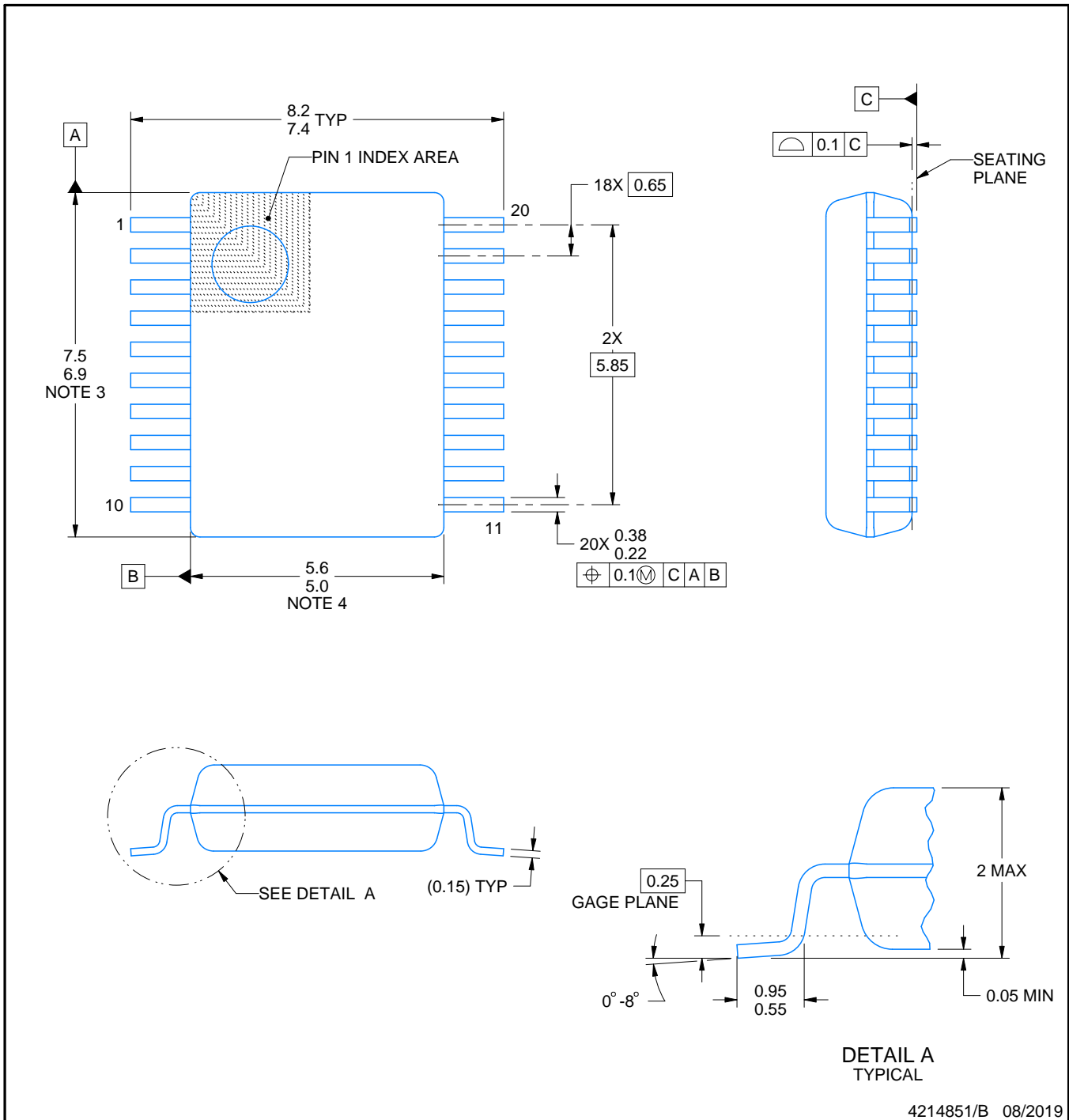
DB0020A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/B 08/2019

NOTES:

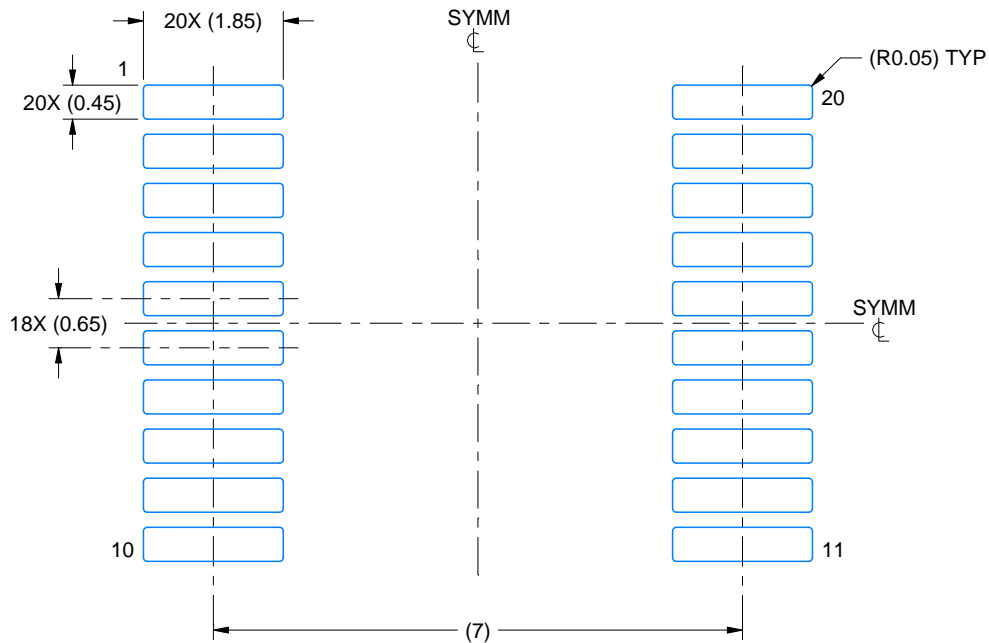
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

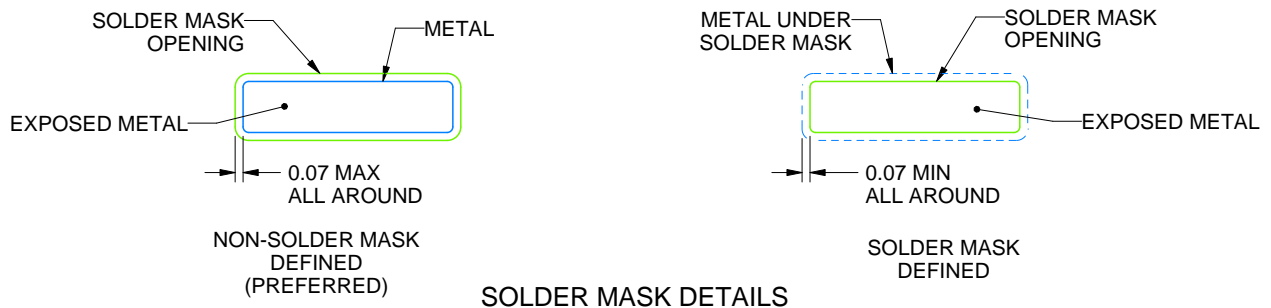
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

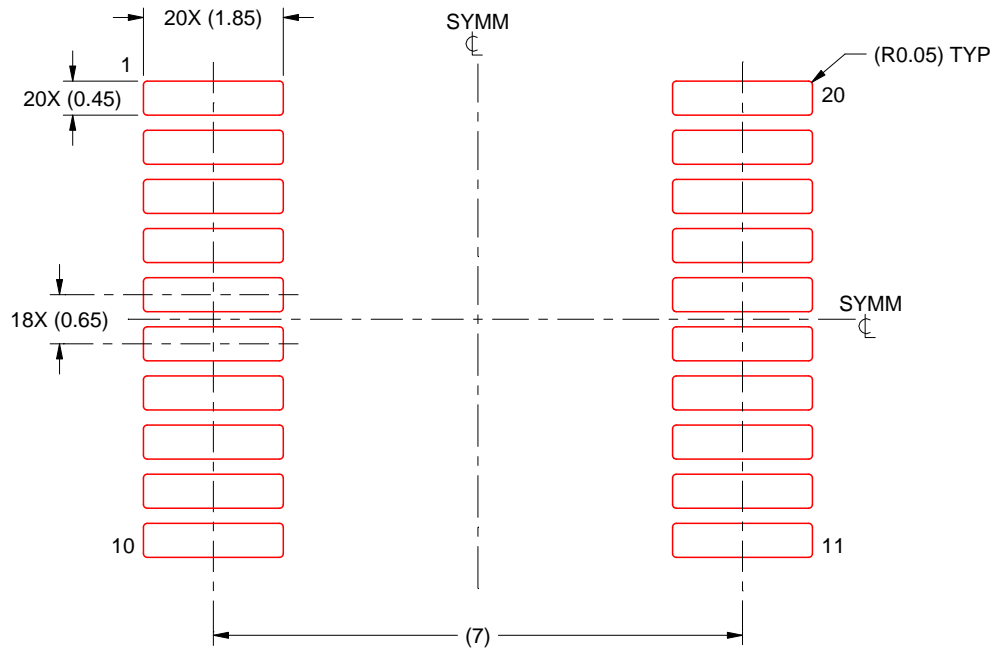
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

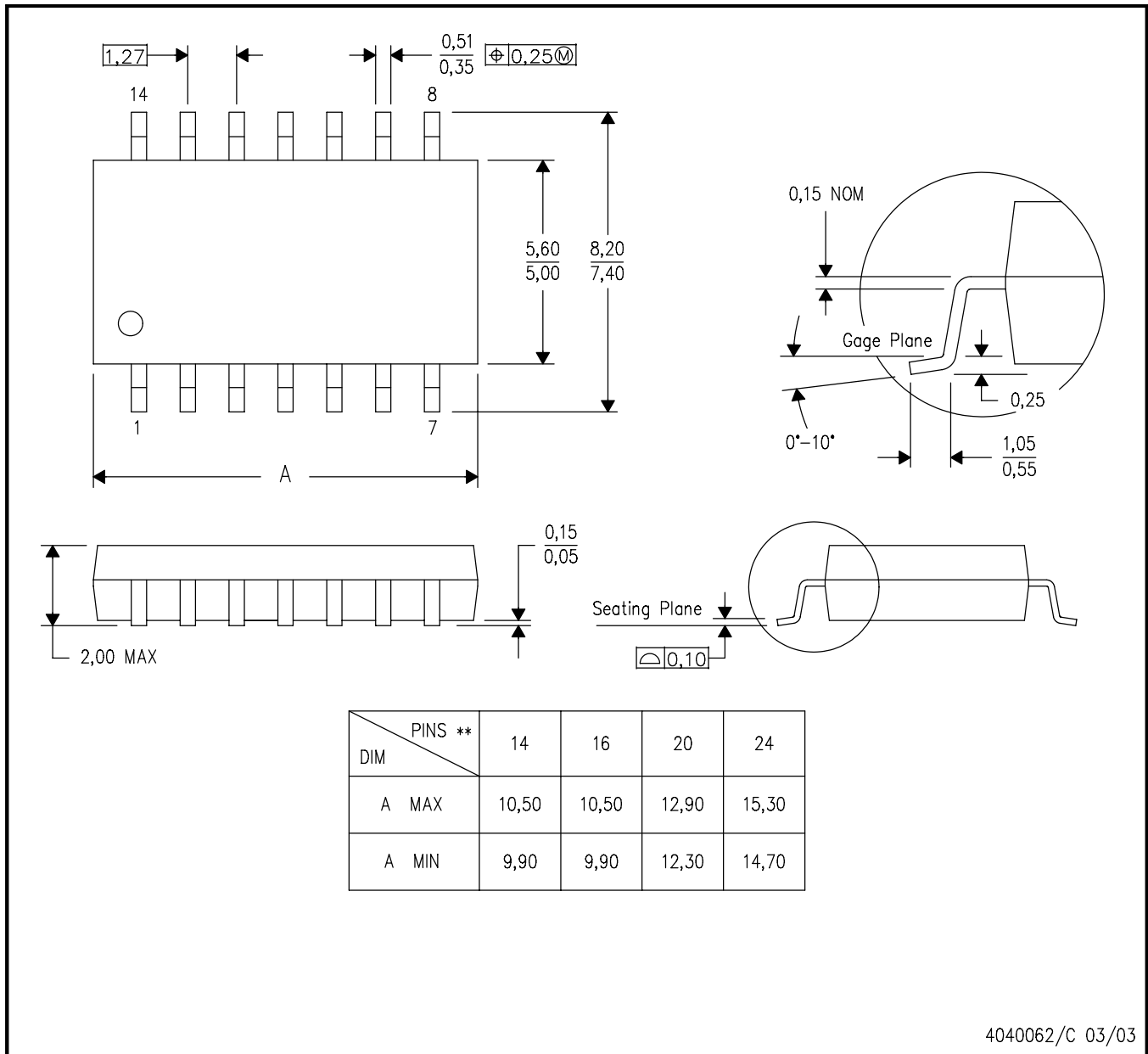
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

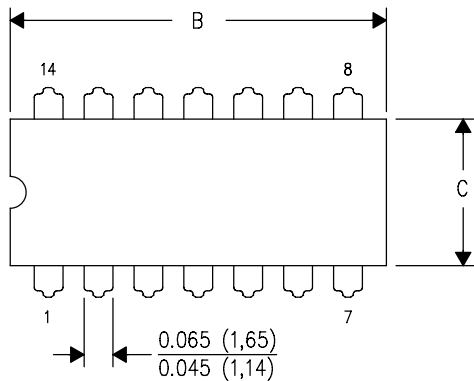


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

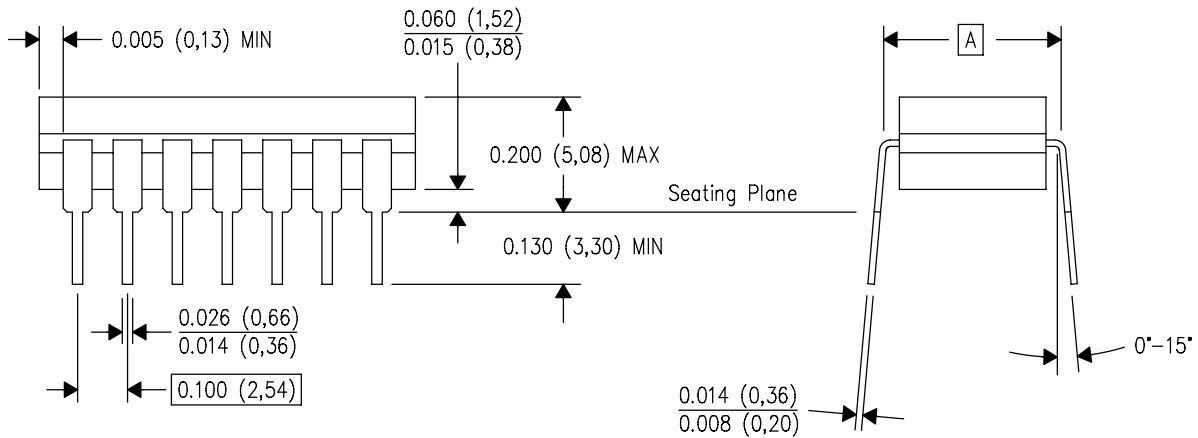
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

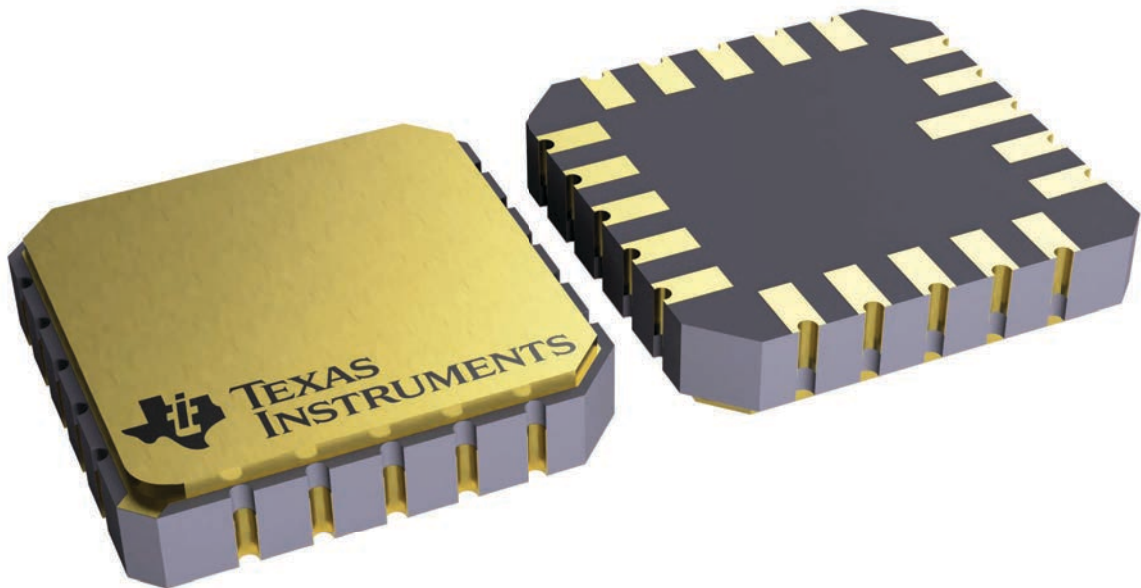
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

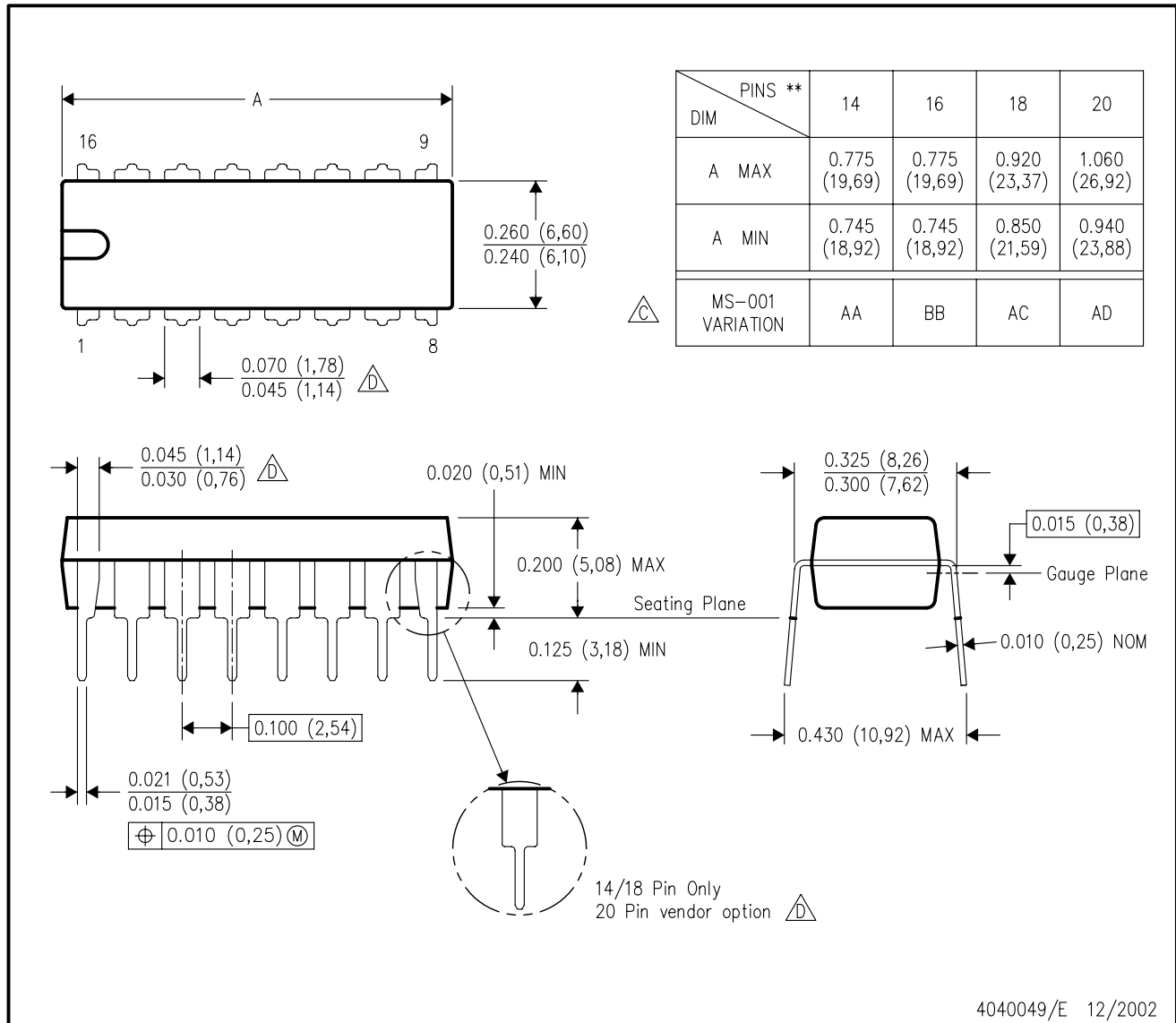


4229370VA\

N (R-PDIP-T**)

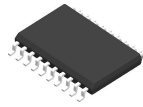
PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

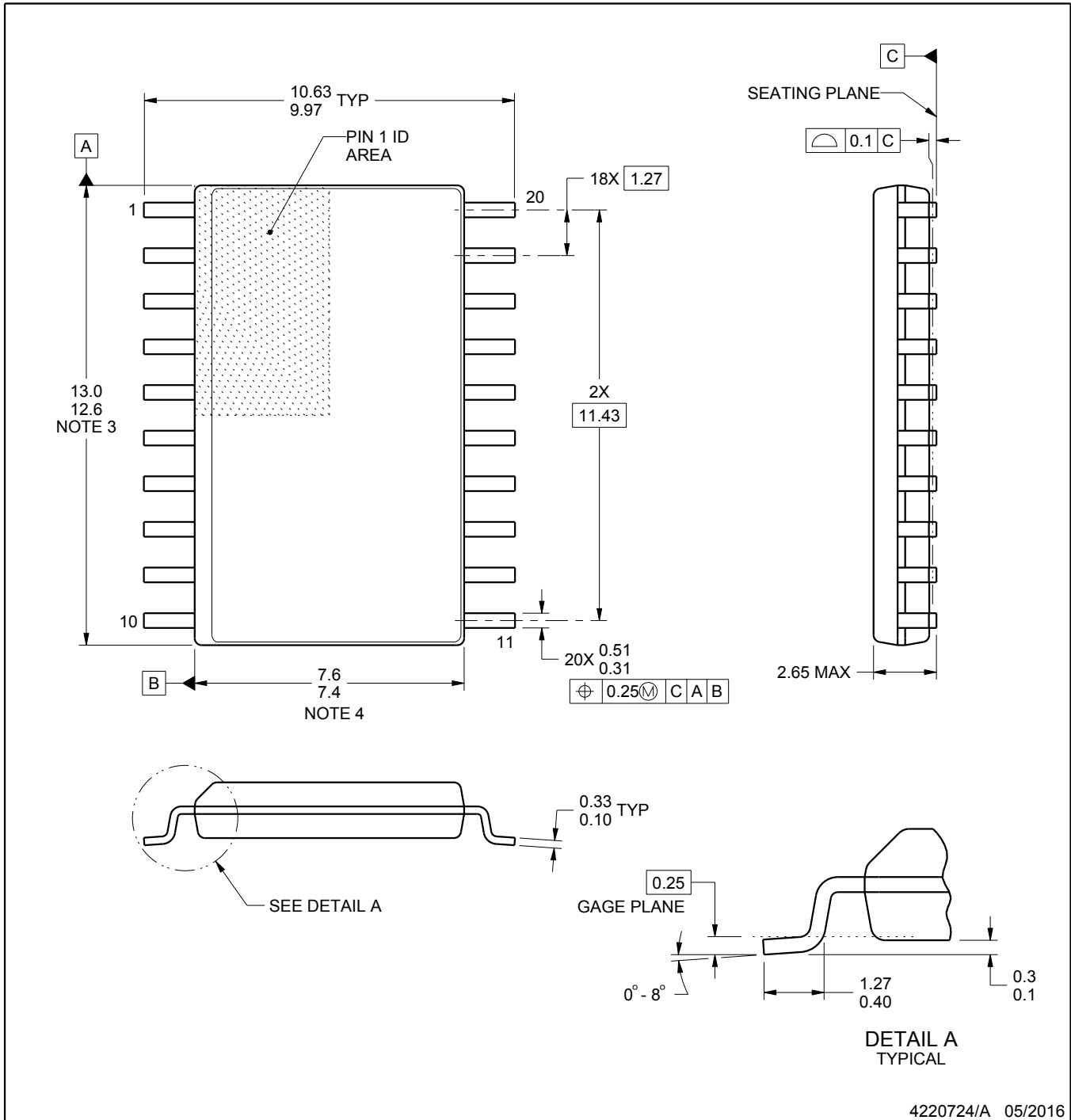
DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

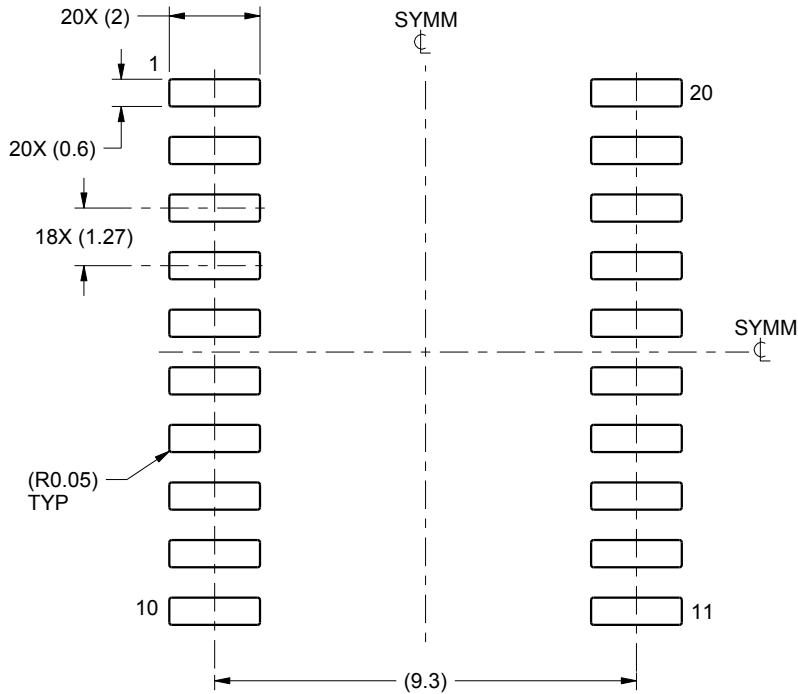
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

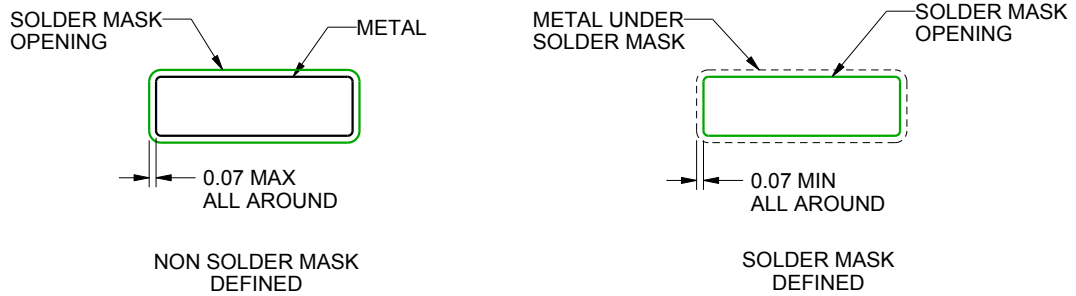
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

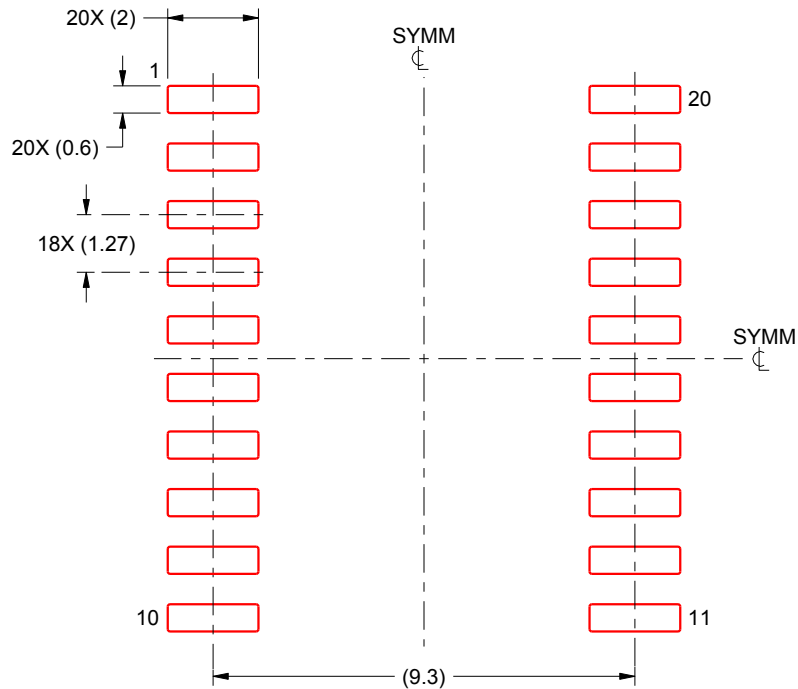
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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